Company :	**Texas Instruments**
Company Name :	**Texas Instruments**
Nature Of Business :	**Engineering & Technology**
Designation :	**Embedded Software Intern**
Tentative Job Location :	Bangalore

Texas Instruments Incorporated is an American technology company that designs and manufactures semiconductors and various integrated circuits. TI is one of the top-10 semiconductor companies worldwide, based on sales volume and is focused on developing analog chips and embedded processors, which account for more than 80% of their revenue. TI has been a pioneer in many innovations in the semi conductor domain including the development of the first integrated circuit; the first patent on a single-chip microprocessor, the first single-chip linear predictive coding speech synthesizer, developing prototype of the world's first transistor radio and the invention of the digital light processing device (also known as the DLP chip), which serves as the foundation for the award-winning DLP technology and DLP Cinema (used in IMAX theatres).

Description :

TI India was set up in 1985 and has R&D presence for all the major business units of TI including Analog - (Data Converters, Amplifiers, Clocks & Synthesizers, Motor Drives, Power Management) and Embedded Processors (Connected Microcontrollers, Radar, ADAS- Advanced Driver Assistance and Infotainment Processors etc.) and caters to products for different market segments - Industrial, automotive, personal Electronics, Communication and Enterprise. The internship will give you a flavor of the real work at TI. You would be assigned to a real time project where in your deliverables will be feed in to the deliverables of your team. You would be assigned a mentor who would work very closely with you and guide you through the entire process.

As an embedded software intern you will have the opportunity to work in one of the many exciting areas that TI works on like ADAS (Advanced Driver Assistance Systems), Radar, Motor Control, DLP, Microcontroller etc. Few examples for projects

1.	**Firmware Architectures for Generating Look-up-tables for Non-Linearity Modeling**
2.	**3D Object Detection**
3.	**Deploying Functional Safety for ADAS SW**
4.	**Realisation of SPI slave module on MCC**
5.	**LwIP integration for low memory footprint network applications**

Eligibilty :

Program	AE	BSBE	CE	CHE	CSE	EE	ES	ME	MSE	PHY	CHM	MTH	ECO	DES	IME	HSS
BT-BS	No	No	No	No	No	Yes	No	No	No	No	No	No	No	--	--	--
MT	No	No	No	No	No	No	No	No	No	--	--	--	--	--	No	--
DoubleMajor	No	No	No	No	No	Yes	No	No	No	No	No	No	No	--	--	--
dual	No	No	No	No	No	Yes	No	No	No	No	No	No	No	--	--	--
dualB	No	No	No	No	--	--	--	No	No	No	No	No	No	--	No	--
dualC	--	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--
Mdes	--	--	--	--	--	--	--	--	--	--	--	--	No	--	--	--
MBA	--	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--
Phd	No	No	No	No	No	No	No	No	No	No	No	No	No	--	--	No
Msc	--	--	--	--	--	--	--	--	No	No	No	No	--	--	--	--
MSR	--	--	--	--	--	--	--	--	--	--	--	--	--	--	--	--

Stipend per month :	**45,000 per month + one time additional 25000 for travel & accommodation**
Other Facilities Offered :	**NA**
Bond :	**False**
CPI CutOff :	**0.0**
Medical Requirments :	
Resume Shortlist :	**False**

Aptitude Test:	**True**
Aptitude Test Duration:	**30**
Group Discussion:	**False**
Technical Test:	**True**
Technical Test Duration:	**45 min**
Technical Interview:	**True**
Technical Interview Duration:	**1 hour**
Number of Techincal Interview Rounds:	**2**
HR Interview:	**True**
HR Interview Duration:	**20 min**
Additional Information:	